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Zhang et al.

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(54) **MIXED ALLOY SOLDER PASTE**

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See application file for complete search history.

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(57) **ABSTRACT**

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(2013.01); **B23K 35/0244** (2013.01); **B23K**
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35/262 (2013.01); **B23K 35/264** (2013.01);
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A solder paste consists of an amount of a first solder alloy
powder between 44 wt % to less than 60 wt %; an amount
of a second solder alloy powder between greater than 0 wt
% and 48 wt %; and a flux; wherein the first solder alloy
powder comprises a first solder alloy that has a solidus
temperature above 260° C.; and wherein the second solder
alloy powder comprises a second solder alloy that has a
solidus temperature that is less than 250° C. In another
implementation, the solder paste consists of an amount of a
first solder alloy powder between 44 wt % and 87 wt %; an
amount of a second solder alloy powder between 13 wt %
and 48 wt %; and flux.

(58) **Field of Classification Search**

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34 Claims, 8 Drawing Sheets

